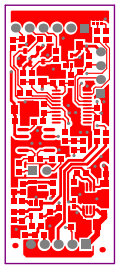
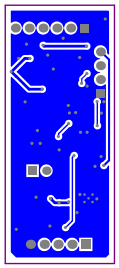
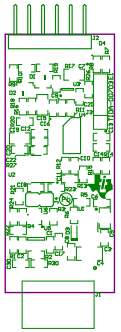


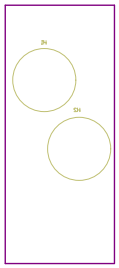
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00703	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #:		
PLOT NAME = Top Layer	GENERATED : 12/7/2015 6:14:55 PM		TEXAS INSTRUMENTS



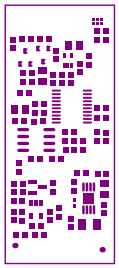
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00703	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:		
PLOT NAME = Bottom Layer	GENERATED : 12/7/2015 6:14:55 PM		TEXAS INSTRUMENTS



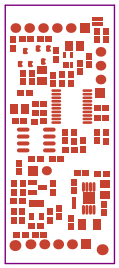
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00703	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #:		
PLOT NAME = Top Silkscreen Overlay	GENERATED : 12/7/2015 6:14:55 PM		TEXAS INSTRUMENTS



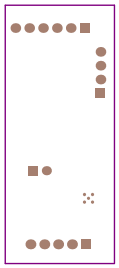
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00703	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #:		
PLOT NAME = Bottom Silkscreen Overlay	GENERATED : 12/7/2015 6:14:56 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00703	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Paste	TID #:		
PLOT NAME = Top Paste Mask Print	GENERATED : 12/7/2015 6:14:56 PM		TEXAS INSTRUMENTS

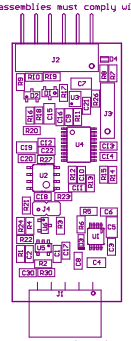


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00703	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #:		
PLOT NAME = Top Solder Mask Print	GENERATED : 12/7/2015 6:14:56 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00703	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #:		
PLOT NAME = Bottom Solder Mask Print	GENERATED : 12/7/2015 6:14:56 PM		TEXAS INSTRUMENTS

Z21 ■These assemblies are ESD sensitive, ESD precautions shall be observed.
Z22 ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
Z23 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00703	REV: E1	SVN REV: Not In VersionControl
M5 Assembly Top	TID #:		
PLOT NAME = M5 Assembly Top	GENERATED : 12/7/2015 6:14:56 PM		TEXAS INSTRUMENTS

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00703	REV: E1	SVN REV: Not In VersionControl
M6 Assembly Bottom	TID #:		
PLOT NAME = M6 Assembly Bottom	GENERATED : 12/7/2015 6:14:57 PM		TEXAS INSTRUMENTS

Layer Stack Up Detail for: TIDA-00703.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil				
			59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

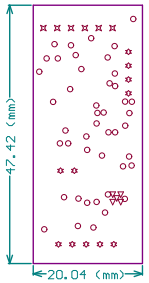
BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
20.04 MM X 47.42 MM

Number of Layers : 2
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 7.874MIL
MIN. VIA DRILL SIZE: 7.874MIL
MINIMUM ANNULAR RING 0.150mm (5.91 MIL)EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER _____
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS --> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS: VIA TENTING: YES [X] NO [ ]
MICROSECTION: [ ] YES IMPEDANCE CONTROL: YES [ ] NO [X]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	5	7.874mil (0.2mm)	PTH	Round
○	45	12mil (0.305mm)	PTH	Round
⌑	6	39.37mil (1mm)	PTH	Round
✡	11	40mil (1.016mm)	PTH	Round
	67 Total			

Drill Table
FOR 7.874MIL DRILL +0/-7.874MIL
FOR 12MIL DRILL +0/-12MIL
FOR PTH DRILL +/-3MIL



NOTES:
7.874MIL DRILL VIAS ARE NOT TENTED.
12MIL DRILL VIAS ARE TENTED IN BOTH SIDES.

TEXAS INSTRUMENTS

PROJECT TITLE: Battery Profiler
DESIGNED FOR: Public Release
FILE NAME: TIDA-00703.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00703	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #:		
PLOT NAME = Drill Drawing For (Bottom Layer): 12/7/2015 6:14:57 PM	GENERATED:		TEXAS INSTRUMENTS

ENGINEER:	LAYOUT BY:
Ramkumar S	Manjunatha T N
SCALE: 0.67	ALTIUM DESIGNER VERSION: 14.3.14.34663

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